Bluetooth Module Datasheet

CZW-5124-03

Model:CZW-5124-03 Hardware Version: V2.0

Release Date: 2019.01.11

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1 summary

CZW-5124-03 is a Bluetooth module designed by ShenZhen Cheng Zhi Wei Technology Co.,Ltd. using Qualcomm Bluetooth chip qcc5124 $_{\circ}$

CZW-5124-03 is a Bluetooth, audio and programmable application processor. It includes high-performance, analog, and digital audio codecs, Class-AB and Class-D headphone drivers, advanced power management, Li-ion battery charger, light-emitting diode (LED) drivers, and flexible interfaces including inter₁ integrated circuit sound (I² S), inter-integrated circuit interface (I² C), universal asynchronous receiver transmitter(UART), and programmable input/output (PIO)_o

CZW-5124-03 package is compatible with czw03 series pins, easy replacement and upgrade

Model Name	CZW-5124-03
Package	60 Pin Module
Dimension	13.8mm x 20.5mm x 2.4mm
Chipset	QCC5124
Bluetooth Version	Bluetooth 5.0
Power Class	Class2
Transmission Distance	≥10M
Voltage	2.8~4.2V
Temperature	-10~+70℃
Storage Temperature	-40∼+85℃
Frequency Range	2402~2480MHz
Maximum RF Transmit Power	9dBm
π/4 DQPSK Receive Sensitivity	-92dBm
8DPSK Receive Sensitivity	-85dBm

2 General specifications

3 Key Features

3.1 Device description

- ★ Quad-core processor architecture
- ★ High-performance Bluetooth® Audio SoC
- ★ Flexible flash programmable platform
- ★ Low power for extended battery life

3.2 Features

- ★ Qualified to Bluetooth® v5.0 specification
- ★ Dual 120 MHz Qualcomm® Kalimba[™] audio DSPs
- ★ 32/80 MHz Developer Processor for applications
- ★ Firmware Processor for system
- ★ Flexible QSPI flash programmable platform
- ★ Advanced audio algorithms
- ★ High-performance 24- bit stereo audio interface
- ★ Digital and analog microphone interfaces
- ★ Active Noise Cancellation: Feedforward, Feedback,Hybrid
- ★ Serial interfaces: UART, Bit Serializer (I² C/SPI), USB 2.0
- ★ Integrated PMU: Dual SMPS for system/digital circuits, Integrated Li-ion battery charger
- ★ 25 PIOs, 5 LED pads with PWM

3.3 Audio subsystem

- ★ Dual 32- bit Kalimba audio digital signal processor (DSP), cores with flexible clocking from 2 MHz to 120 MHz to allow optimization and trade-off performance vs. power consumption
- ★ DSPs execute code from ROM and from program RAM, original equipment manufacturer (OEM) and third party developed features can run from program RAM
- \star 80 KB program RAM
- ★ 256 KB data RAM
- ★ 5 Mb ROM

3.4 Application subsystem

- ★ Dual core application subsystem 32/80 MHz operation
- ★ 32bit Firmware Processor:
- ★ 32bit Developer Processor:
- ★ Both cores execute code from external flash memory using QSPI clocked at 32 MHz or 80 MHz
- ★ On-chip caches per core allow for optimized performance and power consumption

3.5 Bluetooth subsystem

- ★ Qualified to Bluetooth v5.0 specification including 2 Mbps Bluetooth low energy (Production parts)
- ★ Single ended antenna connection with on-chip balun and Tx/Rx switch
- ★ Bluetooth, Bluetooth low energy, and mixed topologies supported
- ★ Class 1 support Li-ion battery charger

3.6 Li-ion battery charger

- ★ Integrated battery charger supporting internal mode (up to 200 mA) and external mode (up to 1.8 A)
- ★ Variable float (or termination) voltage adjustable in 50 mV steps from 3.65 V to 4.4 V
- ★ Thermal monitoring and management are implementable in application software
- ★ Pre-charge to fast charge transition configurable at 2.5 V, 2.9 V, 3.0 V, and 3.1 V Power management

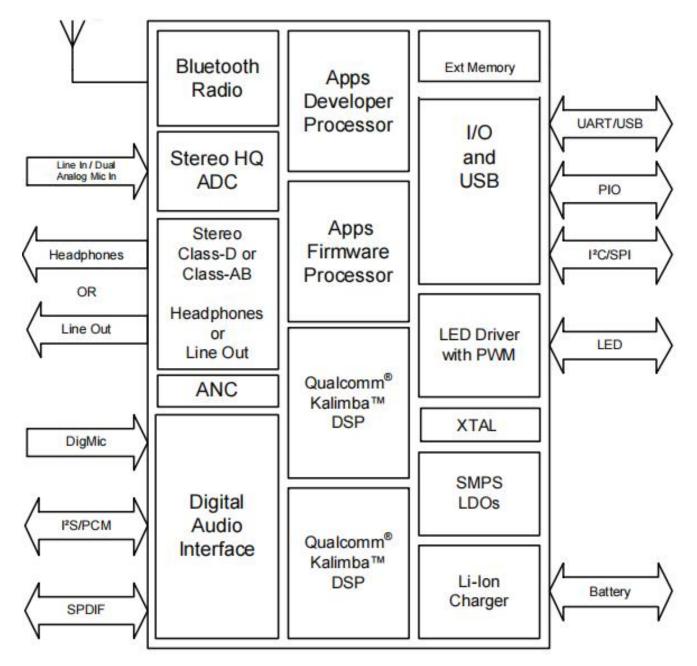
3.7 Power management

- ★ Integrated power management unit (PMU) to minimize external components
- ★ Runs directly from a Li-ion, USB, or external supply (2.8 V to 6.5 V)
- ★ Auto-switching between battery and USB (or other) charging source
- ★ Power islands employed to optimize power consumption for variety of use-cases
- ★ Dual switch-mode power supply (SMPS)

4 Applications

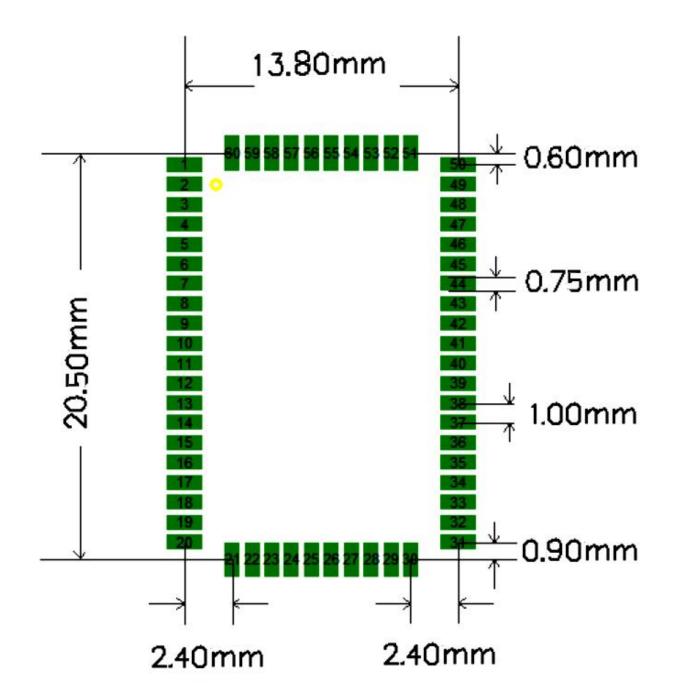
- ★ Wireless speakers
- ★ Wired/wireless stereo headsets/headphones
- ★ Qualcomm TrueWireless™ stereo earbuds
- ★ USB to Bluetooth dongle Features

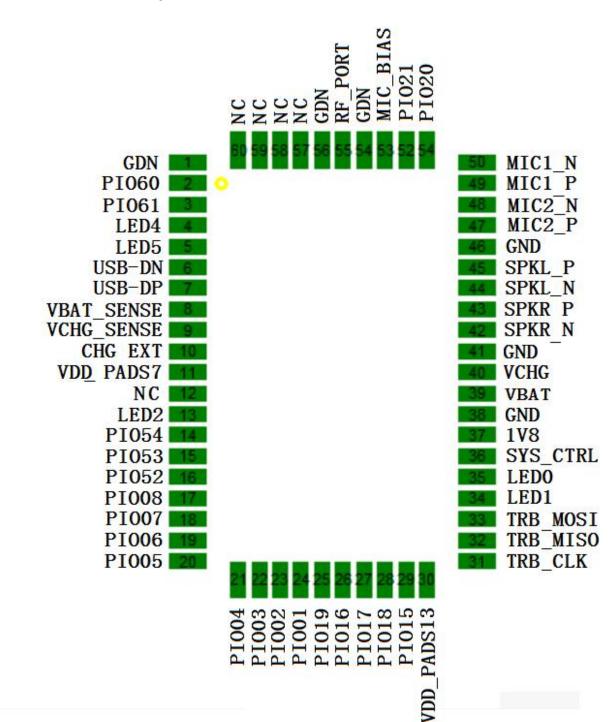
5 Block Diagram



6 Module Package Information

6.1 Pinout Diagram and package dimensions





6.2 Module Pin descriptions

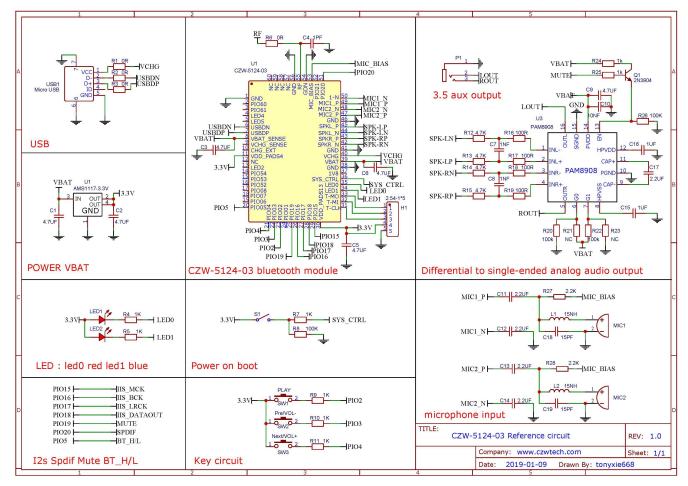
7 Pin Function Description

Pin#	Pin Name	Pin type	Description	
1	GND	Ground	Ground	
2	PIO[60]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 60.	
3	PIO[61]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 61.	
4	LED[4]	Analog or digital input/ open drain output.	General-purpose analog/digital input or open drain LED output.	
5	LED[5]	Analog or digital input/ open drain output.	General-purpose analog/digital input or open drain LED output.	
6	USB_DN	Digital	USB Full Speed device D- I/O. IEC-61000-4-2 (device level) ESD Protection	
7	USB_DP	Digital	USB Full Speed device D+ I/O. IEC-61000-4-2 (device level) ESD Protection	
8	VBAT_SENSE	Analog	Battery voltage sense input.	
9	VCHG_SENSE	Analog	Charger input sense pin after external mode sense-resistor. High impedance. NOTE If using internal charger or no charger, connect VCHG_SENSE direct to VCHG.	
10	CHG_EXT	Analog	External charger transistor current control. Connect to base of external charger transistor as per application schematic.	
11	VDD_PADS_7	Supply	1.8 V/3.3 V PIO supply.	
12	NC	NC	NC	
13	LED[2]	Analog or digital input/ open drain output.	General-purpose analog/digital input or open drain LED output.	
14	PIO[54]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 54. Alternative function: SDIO_D[0]	
15	PIO[53]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 53. Alternative function: SDIO_CMD	
16	PIO[52]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 52. Alternative function: SDIO_CLK	
17	PIO[8]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 8. Alternative function: TBR_CLK	
18	PIO[7]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 7. Alternative function: TBR_MISO[0]	
19	PIO[6]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 6. Alternative function: TBR_MOSI[0]	
20	PIO[5]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 5. Alternative function: TBR_MISO[1]	
21	PIO[4]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 4. Alternative function: TBR_MOSI[1]	

Pin#	Pin Name	Pin type	Description	
22	DIO[2]	Digital: Bidirectional with	Programmable I/O line 3.	
22	PIO[3]	programmable strength internal pull- up/pull-down	Alternative function: TBR_MISO[2]	
23	PIO[2]	Digital: Bidirectional with programmable strength internal	Programmable I/O line 2.	
25		pull- up/pull-down	Alternative function: TBR_MISO[3]	
24	PIO[1]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Automatically defaults to RESET# mode when the device is unpowered, or in off modes. Reconfigurable as a PIO after boot.	
			Alternative function: Programmable I/O line 1	
25	PIO[19]	Digital: Bidirectional with programmable strength internal	Programmable I/O line 19.	
		pull- up/pull-down	Alternative function: PCM_DIN[0]	
26	PIO[16]	Digital: Bidirectional with	Programmable I/O line 16.	
20		programmable strength internal pull- up/pull-down	Alternative function: PCM_CLK	
27	DIO[17]	Digital: Bidirectional with	Programmable I/O line 17.	
27	PIO[17]	programmable strength internal pull- up/pull-down	Alternative function: PCM_SYNC	
20		Digital: Bidirectional with	Programmable I/O line 18.	
28	PIO[18]	programmable strength internal pull- up/pull-down	Alternative function: PCM_DOUT[0]	
		Digital: Bidirectional with	Programmable I/O line 15.	
29	PIO[15]	programmable strength internal pull- up/pull-down	Alternative function: MCLK_OUT	
30	VDD_PADS_1、3	Supply	1.8 V/3.3 V PIO supply.	
• •		Digital: Bidirectional with	TBR_CLK	
31	TBR_CLK	programmable strength internal pull- up/pull-down	Alternative function: Programmable I/O line 8.	
22		Digital: Bidirectional with	TBR_MISO[0]	
32	TBR_MISO	programmable strength internal pull- up/pull-down	Alternative function: Programmable I/O line7.	
22	TOD MOS	Digital: Bidirectional with	TBR_MOSI[0]	
33	TBR_MOS	programmable strength internal pull- up/pull-down	Alternative function: Programmable I/O line6.	
34	LED[1]	Analog or digital input/ open drain	General-purpose analog/digital input or open	
35	LED[0]	output. Analog or digital input/ open drain	drain LED output. General-purpose analog/digital input or open	
	,	output.	drain LED output.	
36	SYS_CTRL	Digital input	Typically connected to an ON/OFF push button. Boots device in response to a button press when power is still present from battery and/or charger but software has placed the device in the OFF or DORMANT state. Additionally useable as a digital input in normal operation. No pull. Additional function: PIO[0] input only	
37	1V8	Supply	1.8V voltage output	
38	GND	Ground	Ground	
39	VBAT	Supply	Battery voltage input.	
40	VCHG	Supply	Charger input to Bypass regulator.	
41	GND	Ground	Ground	

Pin#	Pin Name	Pin type	Description	
42	SPKR N	VDD_AUDIO_HP_ SPKR	Headphone/speaker differential right output, negative.	
			Alternative function: Differential right line output, negative	
			Headphone/speaker differential right output, positive.	
43	SPKR_P	VDD_AUDIO_HP_ SPKR	Alternative function: Differential right line output, positive	
			Headphone/speaker differential left output, negative.	
44	SPKL_N	VDD_AUDIO_HP_ SPKL	Alternative function: Differential left line output, negative	
45	SPKL P		Headphone/speaker differential left output, positive.	
45	SPRL_P	VDD_AUDIO_HP_ SPKL	Alternative function: Differential left line output, positive	
46	GND	Ground	Ground	
47	MIC2_P	VDD AUDIO 1V8	Microphone differential 2 input, positive.	
47			Alternative function: Differential audio line input right, positive	
48	MIC2_N	VDD_AUDIO_1V8 Microphone differential 2 input, negative.		
			Alternative function: Differential audio line input right, negative	
49	MIC1_P	VDD_AUDIO_1V8 Microphone differential 1 input, positive.		
			Alternative function: Differential audio line input left, positive	
50	MIC1_N	VDD_AUDIO_1V8	Microphone differential 1 input, negative.	
			Alternative function: Differential audio line input left, negative	
51	PIO[20]	Digital: Bidirectional with programmable strength internal	Programmable I/O line 20.	
		pull- up/pull-down	Alternative function: PCM_DOUT[1]	
52	PIO[21]	Digital: Bidirectional with programmable strength internal	Programmable I/O line 21.	
53		pull- up/pull-down	Alternative function: PCM_DOUT[2]	
54	MIC_BIAS	VDD_AUDIO_1V8	Mic bias output.	
	GND	Ground	Ground	
55	BT_RF	VDD_BT_RADIO	Bluetooth transmit/receive.	
56	GND	Ground	Ground	
57	NC	NC	NC	
58	NC	NC	NC	
59	NC	NC	NC	
60	NC	NC	NC	

8 Reference application circuit



Notice: for reference only, please design the circuit according to the actual application

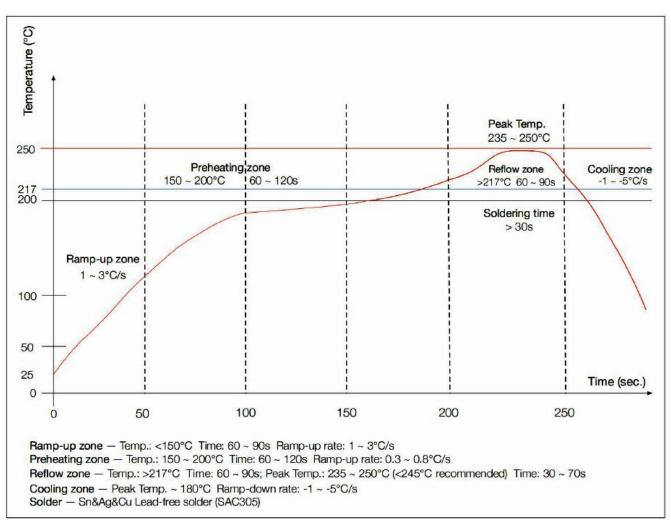
9 Electrical Characteristics

9.1 Absolute Maximum Ratings			
Rating	Minimum	Maximum	
Storage temperature	-40 ℃	+85℃	

9.2 Recommended Operating Conditions

Operating Condition	Minimum	Maximum
Operating temperature range	-40 ℃	+85℃
Supply voltage: VBAT	+2.8V	+4.3V

10 Recommended reflow temperature profile



The module Must go through 100 $^\circ\!\!\!\!{}^\circ\!\!\!{}^\circ$ baking for at least 12 hours before SMT AND IR reflow process!

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